

Neon



**Market Leading Inspection Yield
with Uncompromised Throughput**

Next Generation Inspection Platform optimized for small, fragile semiconductors used in mobility and consumer applications

Neon can handle fragile wafer level chip scale products at high speed, maintaining high operational efficiency while inspecting small devices down to 0.2 x 0.4 mm in size. It features extended process integration capabilities and can be configured with infrared and visual micro-scale defect inspection modules. It is equipped with an external cassette loader / unloader to integrate with factory robots for customers adopting Industry 4.0 initiatives. Designed to provide our customers with the best price/performance ratio in the industry for high volume die needs.

Productivity

- Up to 40,000 UPH with standard 6S inspection
- Up to 38,000 UPH with HR sidewall inspection
- Unique force limitation control for thin and fragile handling at high speed
- Wafer management and Mapfile processing for enhanced traceability
- Cassette loading / unloading Industry 4.0 ready

Flexibility

- Wide Film Frame Carrier applicable device range (0.2 x 0.4 mm to 12 x 12 mm)
- Available in 16 or 32 pickup arms for process optimization
- Up to 23 available turret positions to accommodate required process
- Complete integrated solution for backend finishing process
 - Flip and Non-Flip process capable
 - Detaping to Tape process capable
 - Multi-Taping output capable
 - Full 6 sides inspection

Neon

Ready for Industry 4.0

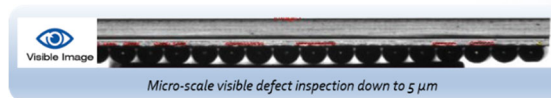
- External cassette loading / unloading for factory robot access



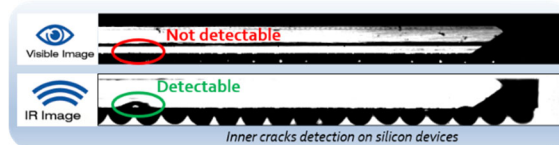
Unique Inspection Applications

- Aquila HR Sidewall Module: micro-scale visible defect inspection down to 5 μm
- Aquila Infrared Module: inner cracks detection on silicon devices
- 3D Flex Vision: true 3-dimensional inspection for Balls/Bumps
- ViewMap: wafer mapping, quality map merging and skeleton check

Aquila HR



Aquila Infrared

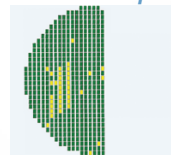


3D Flex



True ball/bump co-planarity

View Map



100% wafer map matching

Available Options

- 16 or 32 Turret pickup arms to fit customer required process
- Flip/Chip module under turret for non-flip process
- Carrier Tape Input for RMA
- 2nd, 3rd Taping Output
- ESD Class 0 with monitoring